

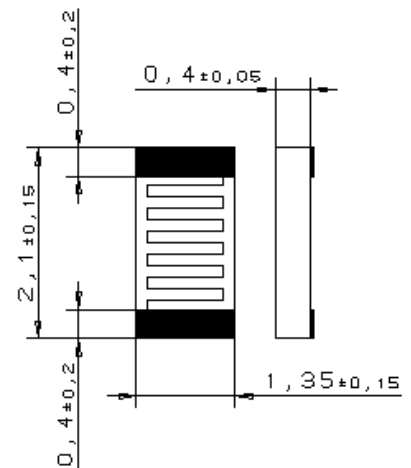
## Platinum Temperature Sensor in Thin Film Technology

## SMD 0805-FC

The main application emphasis of the SMD 805-FC is hybrid circuits. Mass production, precision, long-term stability and low costs are also key themes of the design. The contact surfaces are on the side with the active measuring layer – no edge metallising, i. e. the sensor is designed for face-down mounting, to take into account current trends in the ‘adhesion instead of soldering’ electronics sector. Using conductive adhesives provides reliable and cost-effective connection technology, an alternative to the conventional application opportunities, such as reflow or wave soldering. An important advantage for users: the substrate material of the sensor (ceramic) shows a similar thermal expansion to that of the hybrid circuit.

Nominal Resistance $R_0$	Tolerance	Order No.
100 Ohm at 0 °C	DIN EN 60751, class B	32 208 594
	DIN EN 60751, class 2B	32 208 595
500 Ohm at 0 °C	DIN EN 60751, class B	32 208 598
	DIN EN 60751, class 2B	32 208 599
1000 Ohm at 0 °C	DIN EN 60751, class B	32 208 569
	DIN EN 60751, class 2B	32 208 570

<b>Specification</b>	DIN EN 60751
<b>Tolerance</b>	Class B ( $R_0: \pm 0.12\%$ ), Class 2B ( $R_0: \pm 0.24\%$ )
<b>Temperature range</b>	-50 °C to 170 °C
<b>Temperature coefficient</b>	TCR = 3850 ppm/K
<b>Contact</b>	AgPd metallising in thick-film technology
<b>Long-term stability</b>	$R_0$ drift $\leq 0.06\%$ after 1000 h at 170 °C
<b>Ambient conditions</b>	Use unprotected only in dry environments
<b>Insulation resistance</b>	> 100 M $\Omega$ at 20 °C; > 2 M $\Omega$ at 170 °C (glass cover)
<b>Measuring current</b>	100 $\Omega$ : 0.3 to 1.0 mA 500 $\Omega$ : 0.1 to 0.7 mA 1000 $\Omega$ : 0.1 to 0.3 mA (self heating has to be considered)
<b>Self heating</b>	0.8 K/mW at 0 °C
<b>Reaction time</b>	Flowing water ( $v = 0.4$ m/s): $t_{0.5} = 0.10$ s, $t_{0.9} = 0.25$ s Air flow ( $v = 2$ m/s): $t_{0.5} = 2.5$ s, $t_{0.9} = 8.0$ s
<b>Processing information</b>	- Reflow soldering or wave soldering, e.g. double wave soldering < 8 s / 235° - Also can be mounted using SMD insertion machines with Ag conductive adhesive. - When mounting PCB circuits, the expansion relationship of the sensor and the substrate material must be taken into account.
<b>Storage life</b>	Stored in a nitrogen atmosphere, min. 9 months
<b>Packaging</b>	„Face-down“ in blister reel, 4000 pcs / reel
<b>Note</b>	Other tolerances and values of resistance are available on request.



We reserve the right to make alterations and technical data printed. All technical data serves as a guideline and does not guarantee particular properties to any products.

### Heraeus Sensor Technology USA

770 Township Line Road, Suite 300  
Yardley, PA 19067 USA  
Phone 1-215-944-9010 Fax 1-215-944-9392  
Email [info.hst-us@heraeus.com](mailto:info.hst-us@heraeus.com)  
[www.hst-us.com](http://www.hst-us.com)

Status: HST USA 10/09  
06/2016